# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT7424392

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| **SUBMISSION TYPE:** | NEW ASSIGNMENT |
| **NATURE OF CONVEYANCE:** | ASSIGNMENT |

**CONVEYING PARTY DATA**

| Name | Execution Date |
|---|---|
| YANGANG WANG | 08/04/2021 |
| LUO HAIHUI | 08/12/2021 |

**RECEIVING PARTY DATA**

| | |
|---|---|
| **Name:** | DYNEX SEMICONDUCTOR LIMITED |
| **Street Address:** | DODDINGTON ROAD |
| **Internal Address:** | LINCOLN |
| **City:** | LINCOLNSHIRE |
| **State/Country:** | UNITED KINGDOM |
| **Postal Code:** | LN6 3LF |
| **Name:** | ZHUZHOU CRRC TIMES ELECTRIC CO. LTD. |
| **Street Address:** | TIANXIN BUSINESS PARK |
| **Internal Address:** | ROOM 309 SHIFENG DISTRICT |
| **City:** | ZHUZHOU |
| **State/Country:** | CHINA |

**PROPERTY NUMBERS Total: 1**

| Property Type | Number |
|---|---|
| **Application Number:** | 17430754 |

**CORRESPONDENCE DATA**

**Fax Number:**

***Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.***

**Phone:** 2166212234
**Email:** ainchaurregui@tarolli.com
**Correspondent Name:** CRAIG W. HAYDEN
**Address Line 1:** 1300 EAST 9TH STREET
**Address Line 2:** SUITE 1700
**Address Line 4:** CLEVELAND, OHIO 44114

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|---|---|
| **ATTORNEY DOCKET NUMBER:** | C64-030884-US-PCT |
| **NAME OF SUBMITTER:** | CRAIG W. HAYDEN |

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|---|---|
| **SIGNATURE:** | /Craig W. Hayden/ |
| **DATE SIGNED:** | 07/11/2022 |
| | This document serves as an Oath/Declaration (37 CFR 1.63). |

**Total Attachments: 2**

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# COMBINATION ASSIGNMENT-STATEMENT

## DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

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|---|---|
| Title of Invention: | HIGH POWER DENSITY 3D SEMICONDUCTOR MODULE PACKAGING |

## DECLARATION

As a below named inventor I hereby declare that:

- This declaration is directed to:
  - ☐ The attached application, or
  - X United States application or PCT international application number PCT/CN2020/125889 filed on 2 November 2020.
- The above-identified application was made or authorized to be made by me.
- I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.
- I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

## ASSIGNMENT

WHEREAS, **Dynex Semiconductor Ltd** having an office and place of business at **Doddington Road, Lincoln, Lincolnshire, LN6 3LF, United Kingdom** and **Zhuzhou CRRC Times Semiconductor Co. Ltd** having an office and place of business at **Room 309, Line 3, Tianxin Business Park, Shifeng District, Zhuzhou, Hunan, China** ("ASSIGNEES"), are desirous of jointly acquiring the entire interest in the same;

**NOW, THEREFORE**, in consideration of the sum of £1.00 and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged I, the **INVENTOR**, agree to assign and hereby do sell, assign and transfer unto said **ASSIGNEES** the entire right, title and interest in and to said invention and application throughout the world, including, without limitation, any Letters Patent which may issue thereon, and any subsequent application claiming priority to the above-identified application, reissue, reexamination, divisional, continuation-in-part, extension or continuation thereof and all rights of priority under the Paris Convention arising from said application, and all other rights in said invention possessed by the **INVENTOR**, including the right to bring suit for damages due to past infringements; the same for **ASSIGNEES**' legal representatives and assigns, as fully and entirely as the same would have been held by me had this assignment and sale not been made; to hold unto said **ASSIGNEES** as tenants in common in equal undivided shares;

**AND**, I hereby bind myself, my heirs, legal representatives, administrators and assigns properly to execute without further consideration any and all applications, petitions, oaths and assignments or other papers and instruments which may be necessary in order to carry into full force and effect, the sale, assignment, transfer and conveyance hereby made or intended to be made and generally do everything possible to aid ASSIGNEES, its legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries throughout the world;

**AND**, I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

**AND**, I, the **INVENTOR**, hereby authorize counsel for **ASSIGNEES** to enter above information identifying applications claiming said invention as well as any subsequent application claiming priority directly or indirectly to the above-listed application, including any reissues, reexaminations, divisions, continuations-in-part, extensions, or continuations thereof, and all rights of priority under the International Convention

**LEGAL NAME OF INVENTOR**

Inventor: **Yangang WANG** Date: 04/08/2021

Signature: Ygwang

Attorney Docket No.: ....................

# JOINT DECLARATION - ASSIGNMENT

## DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT FOR SINGLE ASSIGNEE

| | |
|---|---|
| Title of Invention: | High Power Density 3D Semiconductor Module Packaging |

## DECLARATION

As a below named inventor I hereby declare that:

- This declaration is directed to:
  - ☐ The attached application, or
  - ☒ International (PCT) Patent Application No. PCT/CN2020/125889, filed on 02 November 2020.
- The above-identified application was made or authorized to be made by me.
- I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.
- I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 USC 1001 by fine or imprisonment of not more than five (5) years, or both.

## ASSIGNMENT

WHEREAS, **Dynex Semiconductor Ltd** having an office and place of business at **Doddington Road, Lincoln, Lincolnshire, LN6 3LF, United Kingdom** and **Zhuzhou CRRC Times Semiconductor Co. Ltd** having an office and place of business at **Room 309, Line 3, Tianxin Business Park, Shifeng District, Zhuzhou, Hunan, China** (**"ASSIGNEES"**), are desirous of jointly acquiring the entire interest in the same;

**NOW, THEREFORE**, in consideration of the sum of £1.00 and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged I, the **INVENTOR**, agree to assign and hereby do sell, assign and transfer unto said **ASSIGNEES** the entire right, title and interest in and to said invention and application throughout the world, including, without limitation, any Letters Patent which may issue thereon, and any subsequent application claiming priority to the above-identified application, reissue, reexamination, divisional, continuation-in-part, extension or continuation thereof and all rights of priority under the Paris Convention arising from said application, and all other rights in said invention possessed by the **INVENTOR**, including the right to bring suit for damages due to past infringements; the same for **ASSIGNEES'** legal representatives and assigns, as fully and entirely as the same would have been held by me had this assignment and sale not been made; to hold unto said **ASSIGNEES** as tenants in common in equal undivided shares;

**AND**, I hereby bind myself, my heirs, legal representatives, administrators and assigns properly to execute without further consideration any and all applications, petitions, oaths and assignments or other papers and instruments which may be necessary in order to carry into full force and effect, the sale, assignment, transfer and conveyance hereby made or intended to be made and generally do everything possible to aid **ASSIGNEES**, its legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries throughout the world;

**AND**, I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

**AND**, I, the **INVENTOR**, hereby authorize counsel for **ASSIGNEES** to enter above information identifying applications claiming said invention as well as any subsequent application claiming priority directly or indirectly to the above-listed application, including any reissues, reexaminations, divisions, continuations-in-part, extensions, or continuations thereof, and all rights of priority under the International Convention.

**LEGAL NAME OF INVENTORS**

Inventor: Luo Haihui Date: 12/08/2021

Signature: ....................